

**Electronic Patent Application Fee Transmittal**

<b>Application Number:</b>	10623679			
<b>Filing Date:</b>	22-Jul-2003			
<b>Title of Invention:</b>	Resist pattern thickening material, resist pattern and process for forming the same, and semiconductor device and process for manufacturing the same			
<b>First Named Inventor/Applicant Name:</b>	Koji Nozaki			
<b>Filer:</b>	Shuji Yoshizaki			
<b>Attorney Docket Number:</b>	030891			
Filed as Large Entity				
<b>Utility under 35 USC 111(a) Filing Fees</b>				
<b>Description</b>	<b>Fee Code</b>	<b>Quantity</b>	<b>Amount</b>	<b>Sub-Total in USD(\$)</b>
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
Claims in excess of 20	1202	1	52	52
Independent claims in excess of 3	1201	1	220	220
<b>Miscellaneous-Filing:</b>				
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				
<b>Post-Allowance-and-Post-Issuance:</b>				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Extension-of-Time:</b>				
Extension - 2 months with \$0 paid	1252	1	490	490
<b>Miscellaneous:</b>				
<b>Total in USD (\$)</b>				<b>762</b>